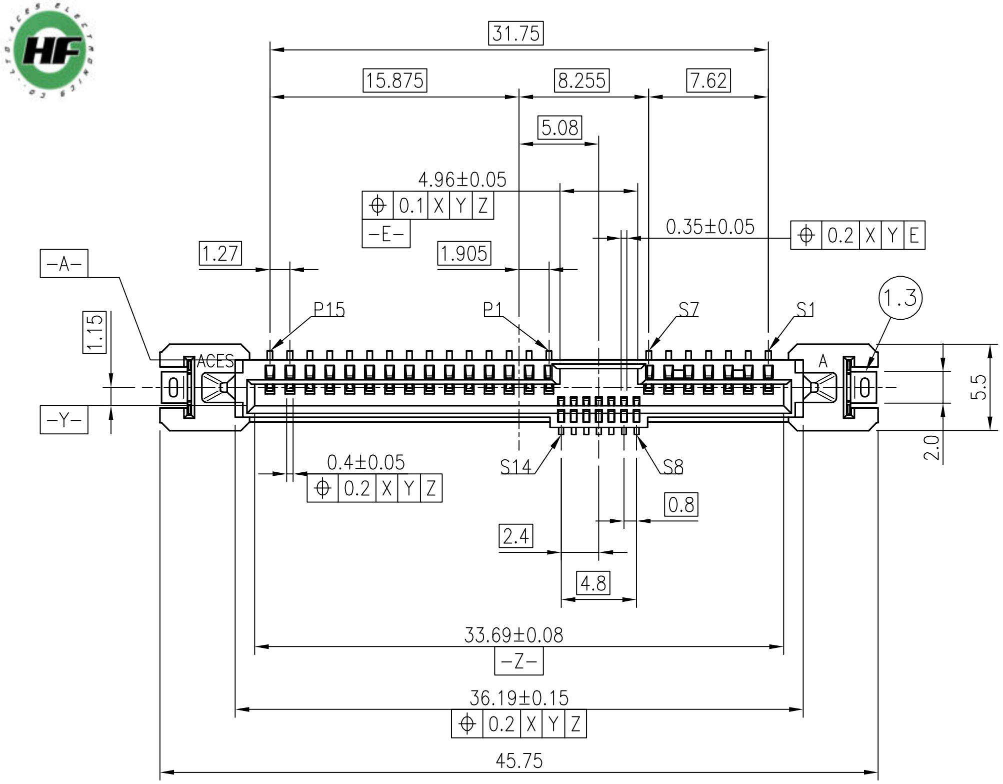
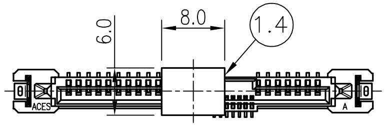
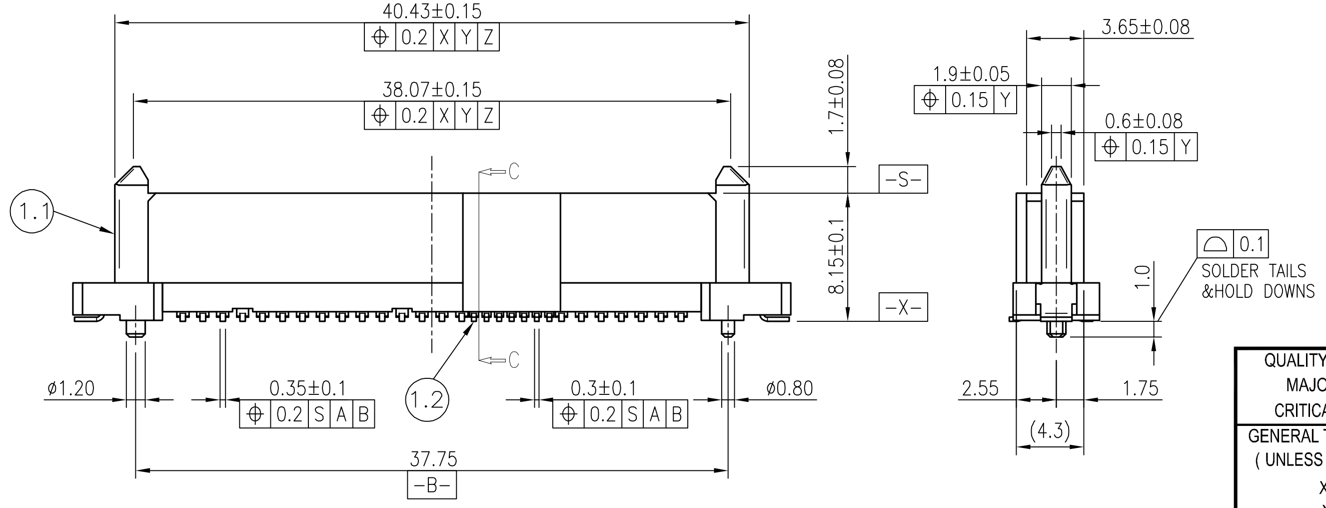


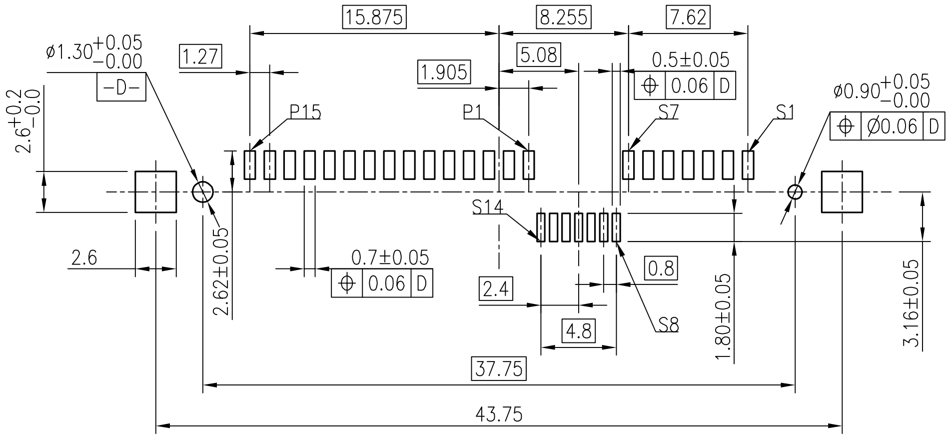
NOTES:
1. MATERIAL:
  1.1 HOUSING: THERMOPLASTIC, HIGH TEMP.,UL94V-0; COLOR:BLACK.
  1.2 CONTACT: COPPER ALLOY
  1.3 HOLD DOWN: COPPER ALLOY
  1.4 PICK-UP CAP: THERMOPLASTIC, HIGH TEMP.,UL94V-0; COLOR:BLACK.
2. FINISH:
  2.1 CONTACT:
    GOLD PLATING ON CONTACT AREA.
    100~200u" MATTE TIN PLATING ON SOLDER TAILS.
    50~100u" NICKEL UNDERPLATING OVERALL.
  2.2 HOLD DOWN:
    100~200u" MATTE TIN PLATING ON SOLDER TAILS.
    50~100u" NICKEL UNDERPLATNG OVERALL.
3. REFLOW SOLDER CAPABLE TO 260°C ,PER ACES SPEC.
4. SPEC. PLS. REFER TO PS-51891-XXXXX-XXX
5. PACKAGE PLS. REFER TO 51891-XXXXX-XX-TRP
6. PART NUMBER
    51901-029 X X-XXX
    NO OF CKT — 029
    TYPE — 001: NONE
    PLATING — D: 30u" GOLD PLATING
    PACKING — 0:TAPE&REEL



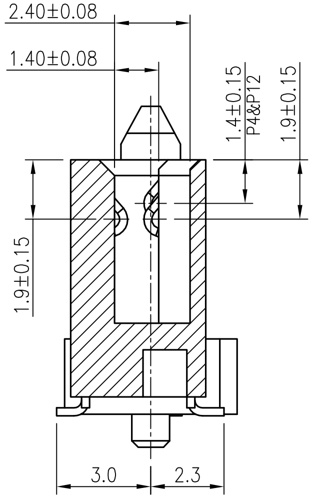
WITH PICK-UP CAP
SCALE 1:1



QUALITY SYMBOLS MAJOR Ⓜ CRITICAL Ⓒ	DRAWN BY / DATE Lin, Chia Ann 22'/07/26	ACES ELECTRONICS		
GENERAL TOLERANCES (UNLESS SPECIFIED)	CHECKED BY / DATE Lee, I Hung 22'/07/26	TITLE 1.27/0.8 PITCH SAS 12G RECEPTACLE VERTICAL SMT TYPE		
X. ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	APPROVED BY / DATE Wang, Chun Sheng 22'/07/26			
	UNITS mm	⌖ ⊏	SIZE A4	RFQ NO. -
	SCALE 2 : 1	SHEET NO. 1 OF 2	REV A	DWG NO. 51901-029XX-XXX



RECOMMENDED P.C.B. LAYOUT



SECTION C–C
SCALE 4:1

QUALITY SYMBOLS MAJOR Ⓜ CRITICAL Ⓒ	DRAWN BY Lin, Chia Ann	DATE 22'/07/26	ACES ELECTRONICS	
	CHECKED BY Lee, I Hung	DATE 22'/07/26		
GENERAL TOLERANCES (UNLESS SPECIFIED)	APPROVED BY Wang, Chun Sheng	DATE 22'/07/26	TITLE 1.27/0.8 PITCH SAS 12G RECEPTACLE VERTICAL SMT TYPE	
X. ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	UNITS mm	⊕ ⊏⊐	SIZE A4	RFQ NO. -
	SCALE 2 : 1	SHEET NO. 2 OF 2	REV A	DWG NO. 51901-029XX-XXX